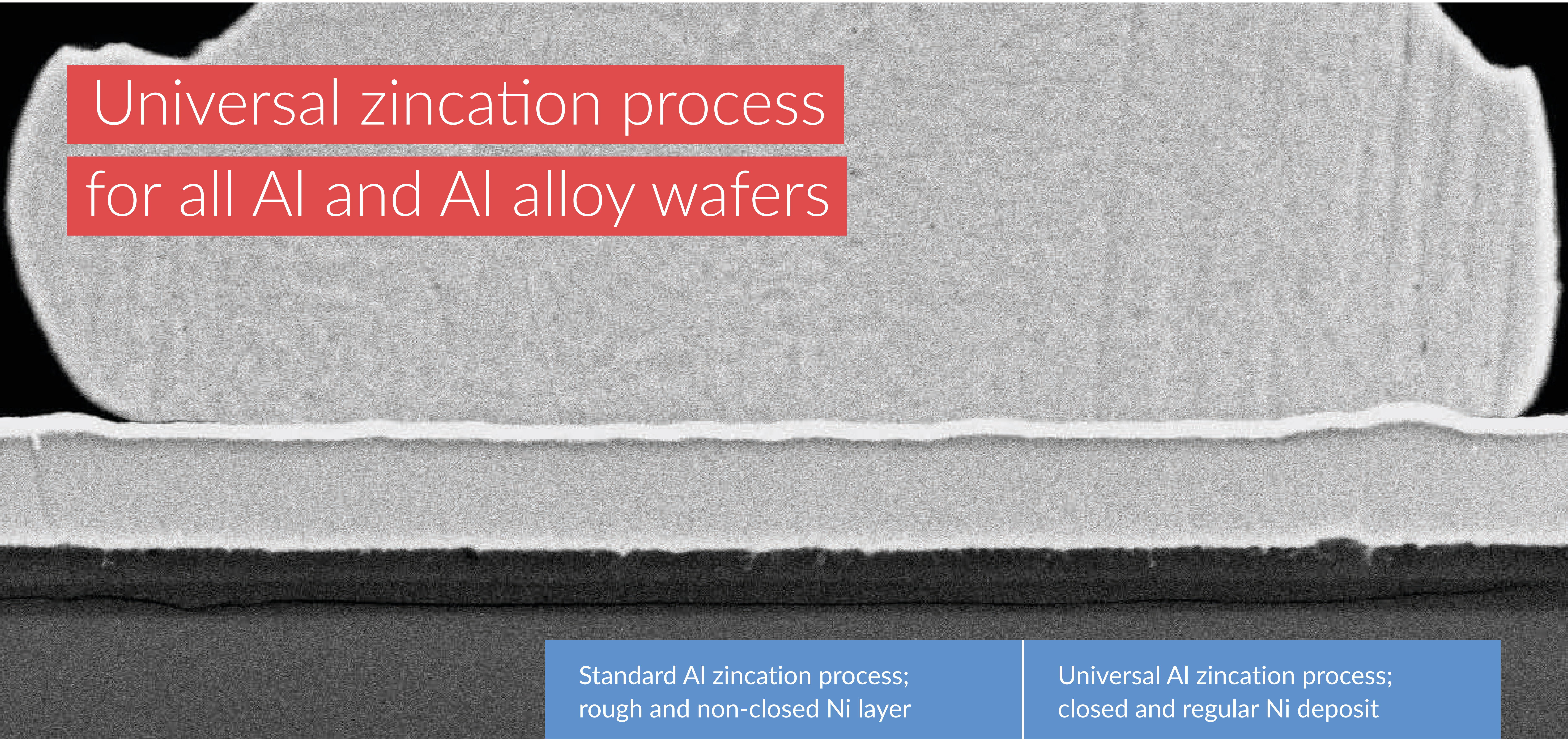
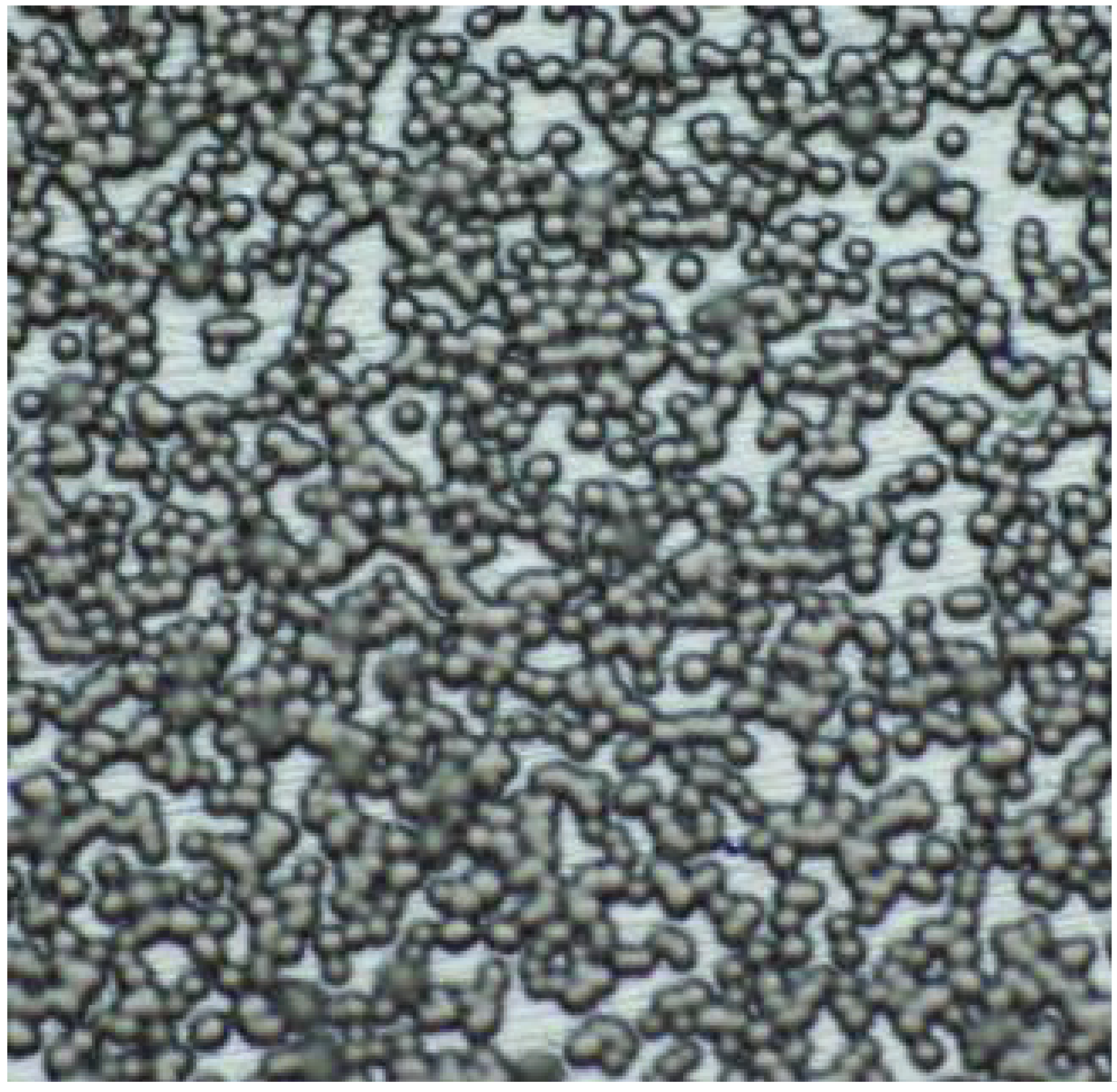
Xenolyte® Zincate CFA2

mks
Atotech



Universal zincation process for all Al and Al alloy wafers

Standard Al zincation process; rough and non-closed Ni layer



Universal Al zincation process; closed and regular Ni deposit

Suitable for all Al, AlSi, and AlSiCu wafers

Power chips and discretes for automotive and energy conversion industries

Universal acidic zincation

Xenolyte® Zincate CFA2 is a universal pretreatment process for all types of Al and Al alloy wafers. The pretreatment is the first step for an ENEPIG or ENIG metallization (electroless nickel, electroless palladium, immersion gold). It removes the oxide layer of Al and replaces it with a zinc layer of several nanometers. Following pretreatment, the zinc layer may be plated with electroless nickel for further metallization.

Features and benefits

- Sufficient oxide removal and homogeneous zincation
- Compatible with all solder mask and resist types
- No Ag migration
- No harmful, volatile ingredients